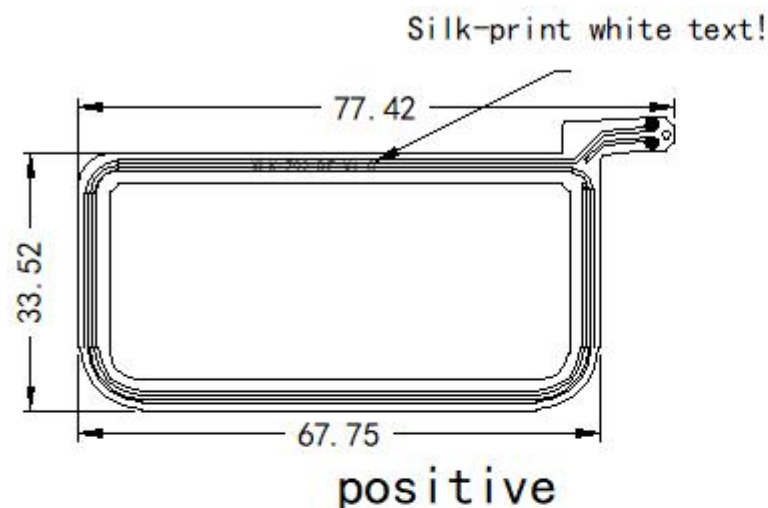
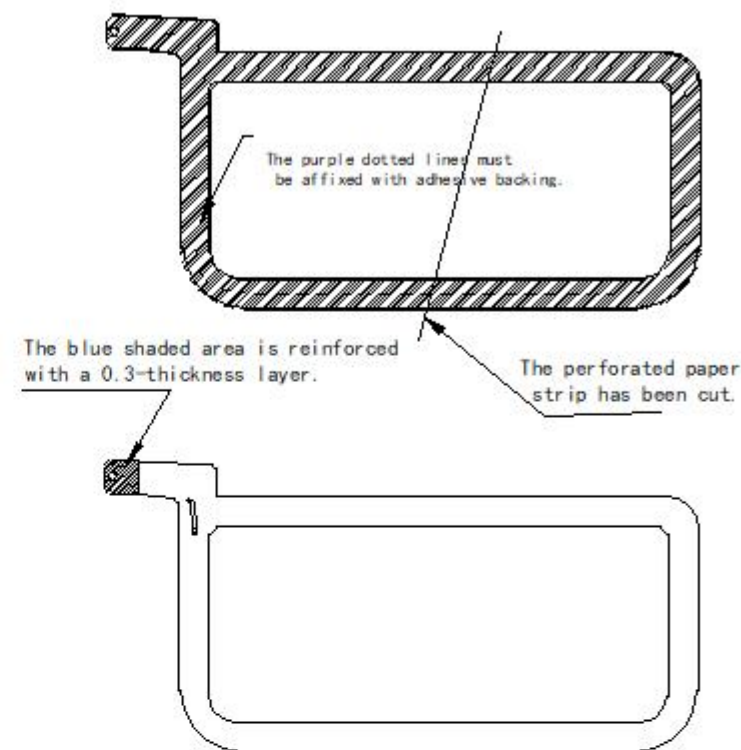


Item number:Y.ZZ.XC.0010128



Technical Requirements:

1. Material: FPC (dual-layer board, black oil with half-electrolytic copper substrate), $T < 0.15$ mm; Backside adhesive type: 3M9471 (adhesive performance requires heat shock testing).
2. Dimensions marked with an asterisk (*) are subject to special control measures. If no tolerance is specified, it will be governed by the free tolerance within the drawing frame. Dimensions not specified will be verified based on the film inspection (electrical performance must be tested and confirmed as satisfactory).
3. The thickness of the electroplating process shall be 0.5μ ". It must not exhibit any undesirable phenomena such as easy breakage and detachment after gold plating, poor conductivity, or breaks in the circuitry.
4. The surface ink on the FPC must be uniform, free of contaminants, scratches, black spots, wrinkles, and other defects such as poor gold plating.
5. The product complies with the ROHS standard.



The other side

Shenzhen New Link Technology Co., Ltd

				Third-person perspective		entry name:		date		2022-12-07	
				0.03		Z92		Design		Zsb	
				0.03		Product name:		To examine		MD	
				0.02		NFC				RF	
				0.02				Approval			
				0.05							
Page 1 of 1.						Material Science:		unit:mm		proportion:FIT	
						FPC					